

NTAG203

NFC Forum Type 2 Tag compliant IC with 144 bytes user memory

Rev. 3.2 — 12 December 2011
218632

Product short data sheet
COMPANY PUBLIC

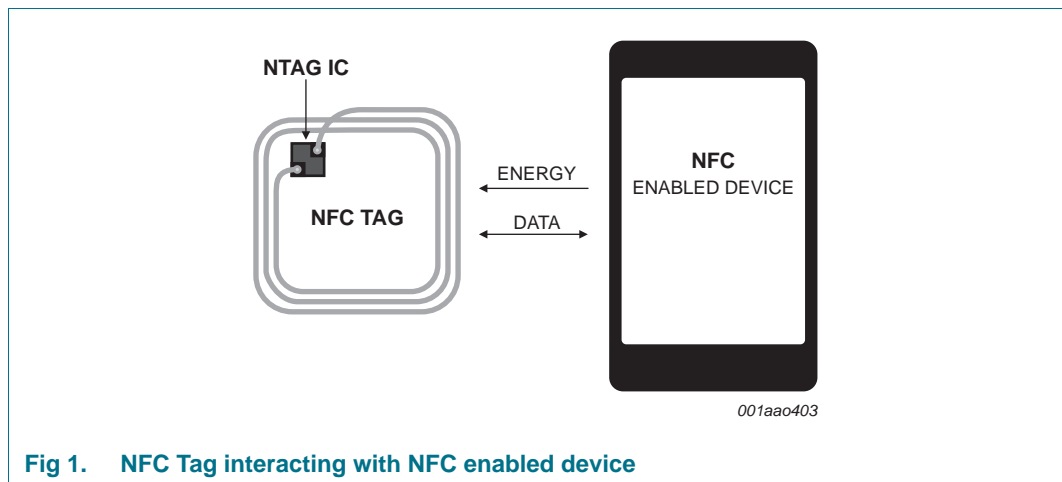
1. General description

NXP Semiconductors has developed NTAG203 - NFC Forum Type 2 Tag compliant IC - to be used with NFC enabled devices according to NFC Forum technical specifications (see [Ref. 9](#) and [Ref. 10](#)), according to NFC Forum recommendations or Proximity Coupling Devices (PCD), according to ISO/IEC 14443A (see [Ref. 2](#)). The communication layer (RF Interface) complies to parts 2 and 3 of the ISO/IEC 14443A standard. The NTAG203 is primarily designed for NFC Forum Type 2 Tag applications (i.e. Smart Advertisement, connection handover, Bluetooth simple pairing, WiFi Protected set-up, call request, SMS, goods and device authentication and others).

1.1 Contactless energy and data transfer

Communication to NTAG can be established only when the IC is connected to a coil. Form and specification of the coil is out of scope of this document.

When the NTAG is positioned in the RF field, the high speed RF communication interface allows the transmission of the data with a baud rate of 106 kbit/s.



1.2 Naming conventions

Table 1. Short naming convention (for easier product identification)

| Family name | Description |
|-------------|---|
| NTAG | NXP NFC Tag product family name |
| 2 | Platform indicator |
| 0 | Generation number (starting from 0) |
| 3 | Code number for memory size (0 : < 64 bytes, 1 : 64-96 bytes; 2 : 96-128 bytes; 3 : 128-256 bytes) |
| F | Delivery option: if stated, it is a HWSO8 package with Field Detection pin |

2. Features and benefits

2.1 RF Interface (ISO/IEC 14443A)

- Contactless transmission of data and supply energy (no battery needed)
- Operating distance: up to 100 mm (depending on field strength and antenna geometry)
- Operating frequency: 13.56 MHz
- Fast data transfer: 106 kbit/s
- High data integrity: 16-bit CRC, parity, bit coding, bit counting
- True anticollision
- 7 byte serial number (cascade level 2 according to ISO/IEC 14443-3)

2.2 EEPROM

- 168 bytes of total memory, divided in 42 pages (4 bytes each)
- 144 bytes of user r/w memory area, divided in 36 pages (4 bytes each)
- Field programmable read-only locking function per page for first 64 bytes
- Field programmable read-only locking function per block
- 32-bit user definable One-Time Programmable (OTP) area
- 16-bit counter
- Data retention of 5 years
- Write endurance 10000 cycles

2.3 NFC Forum Tag 2 Type compliance

NTAG203 IC provides full compliance to the NFC Forum Tag 2 Type technical specification (see [Ref. 9](#)) and enables NDEF data structure configurations (see [Ref. 10](#)).

2.4 Security

- Anti-cloning support by unique 7-byte serial number for each device
- 32-bit user programmable OTP area
- Field programmable read-only locking function per page for first 512 bits
- Read-only locking per block for rest of memory

2.5 Cascaded UID

The anticollision function is based on an IC individual serial number called Unique Identifier. The UID of the NTAG203 is 7 bytes long and supports cascade level 2 according to ISO/IEC 14443-3.

2.6 Anticollision

An intelligent anticollision function according to ISO/IEC 14443 allows to operate more than one card in the field simultaneously. The anticollision algorithm selects each card individually and ensures that the execution of a transaction with a selected card is performed correctly without data corruption resulting from other cards in the field.

3. Quick reference data

Table 2. Quick reference data

In accordance with the Absolute Maximum Rating System (IEC 60134).^{[1][2][3]}

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|-------------------|---|-------|-------|-----|-------|
| f_i | input frequency | | - | 13.56 | - | MHz |
| C_i | input capacitance | 50 pF version (bare silicon and HWSO8) ^[4] | 44 | 50 | 56 | pF |
| EEPROM characteristics | | | | | | |
| $t_{cy(W)}$ | write cycle time | | - | 4.1 | - | ms |
| t_{ret} | retention time | $T_{amb} = 22\text{ °C}$ | 5 | - | - | year |
| $N_{endu(W)}$ | write endurance | $T_{amb} = 22\text{ °C}$ | 10000 | - | - | cycle |

[1] Stresses above one or more of the limiting values may cause permanent damage to the device.

[2] These are stress ratings only. Operation of the device at these or any other conditions above those given in the Characteristics section of the specification is not implied.

[3] Exposure to limiting values for extended periods may affect device reliability.

[4] LCR meter HP 4285, $T_{amb} = 22\text{ °C}$, Cp-D, $f_i = 13.56\text{ MHz}$, 2Veff.

4. Ordering information

Table 3. Ordering information

| Type number | Package | | Version |
|---------------|---------|--|---------|
| | Name | Description | |
| NT2H0301G0DUD | wafer | 8 inch wafer (sawn, laser diced; 120 μm thickness, on film frame carrier; electronic fail die marking according to SECSII format) | - |

5. Block diagram

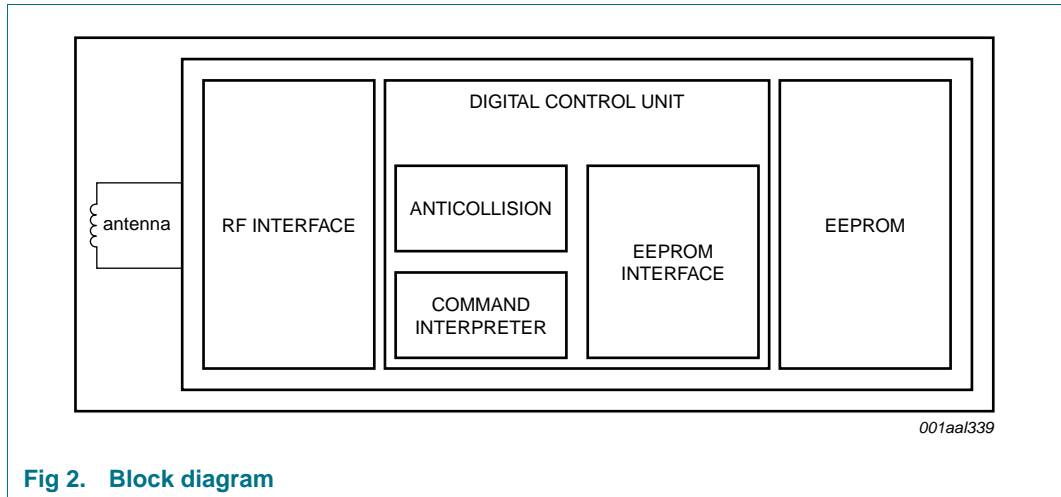


Fig 2. Block diagram

6. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).^{[1][2]}

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------------|-----------------------|------------------|------|------|
| I_I | input current | | - | 30 | mA |
| T_{stg} | storage temperature | | -55 | +125 | °C |
| T_{amb} | ambient temperature | | -25 | +70 | °C |
| V_{ESD} | electrostatic discharge voltage | measured on pin LA-LB | ^[3] 2 | - | kV |

[1] Stresses above one or more of the limiting values may cause permanent damage to the device.

[2] Exposure to limiting values for extended periods may affect device reliability.

[3] MIL Standard 883-C method 3015; Human body model: C = 100 pF, R = 1.5 kΩ.

7. References

- [1] **Data sheet** — NTAG203 NFC Forum Type 2 Tag compliant IC with 144 bytes user memory, BU-ID Doc.No.: 2138**1
- [2] **ISO/IEC** — International Organization for Standardization/International Electrotechnical Commission
- [3] **Interface Platform Type Identification Procedure** — Application note, BU-ID Doc. No.: 0184**
- [4] **ISO/IEC 14443 PICC Selection** — Application note, BU-ID Doc. No.: 1308**
- [5] **Ultralight Features and Hints** — Application note, BU-ID Doc. No.: 0731**
- [6] **Ultralight as Type 2 Tag** — Application note, BU-ID Doc. No.: 1303**
- [7] **(Card) Coil Design Guide** — Application note, BU-ID Doc. No.: 0117**

1. ** ... document version number

- [8] **MF01CU1 Functional specification MIFARE Ultralight** — Product data sheet, BU-ID Doc. No. 0286**
- [9] **Tag 2 Type Operation, Technical Specification** — NFC Forum, 09.07.2007
- [10] **NFC Data Exchange Format (NDEF), Technical Specification** — NFC Forum, 24.07.2006
- [11] **NXP Semiconductors guidance for soldering the HWSO8 package; URL: [http://www.nxp.com/#/page/content=\[f=/packages/SOT1069-2.xml\]](http://www.nxp.com/#/page/content=[f=/packages/SOT1069-2.xml])** — NXP Semiconductors, 21.08.2009

8. Revision history

Table 5. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------------|--|--------------------------|---------------|-------------------|
| NTAG203_SDS v.3.2 | 20111212 | Product short data sheet | - | NTAG203_SDS v.3.1 |
| Modifications: | <ul style="list-style-type: none">• Section 9.4 "Licenses": added | | | |
| NTAG203_SDS v.3.1 | 20111206 | Product short data sheet | - | NTAG203_SDS v.3.0 |
| Modifications: | <ul style="list-style-type: none">• Table 3 "Ordering information": Type number changed from MF0ICU1701NDUD into NT2H0301G0DUD• Section 7 "References": updated | | | |
| NTAG203_SDS v.3.0 | 20111019 | Product short data sheet | - | - |

9. Legal information

9.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 12 December 2011
218632